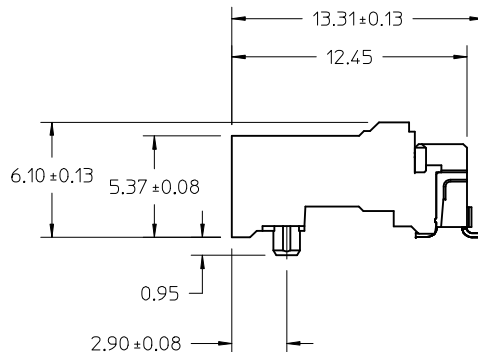
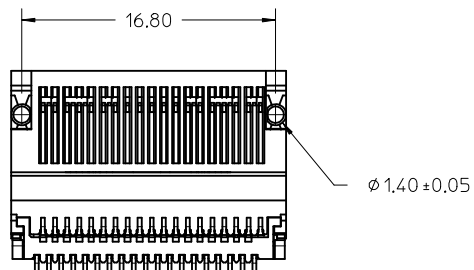
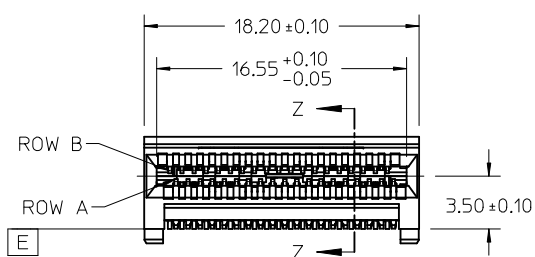
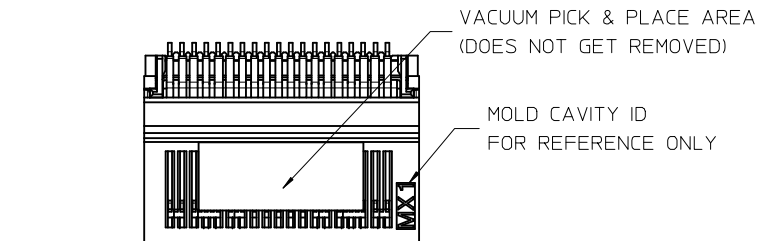


SECTION Z-Z
SCALE 5:1

NOTES

1. MATERIAL:

HOUSING - HIGH TEMPERATURE THERMOPLASTIC GLASS FILLED,
UL 94V-0, BLACK
TERMINALS - COPPER ALLOY

2. PLATING:

CONTACT AREA - 0.38 μ m MIN GOLD OVER 2.54 μ m MIN NICKEL
SOLDER FOOT AREA - 2.54 - 5.09 μ m TIN OVER 2.54 μ m MAX NICKEL.

3. PLATING:

CONTACT AREA - 0.76 μ m MIN GOLD OVER 2.54 μ m MIN NICKEL
SOLDER AREA - 2.54 - 5.09 μ m TIN OVER 2.54 μ m MAX NICKEL

4. PLATING:

CONTACT AREA - 0.76 μ m MIN GOLD OVER 2.54 μ m MIN NICKEL,
SOLDER AREA: GOLD FLASH OVER 2.54 μ m MAX NICKEL.

5. TERMINAL SOLDER FEET TO BE COPLANAR WITHIN 0.10/0.04 MEASURED FROM FRONT HOUSING STAND OFF (DATUM E)

6. DATE CODE: 4 DIGIT (3 DIGIT DATE, 1 DIGIT YEAR)

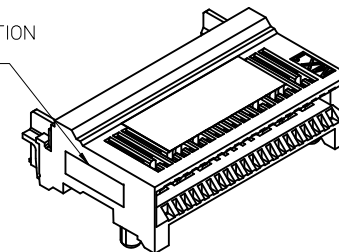
7. CIRCUIT IDENTIFIER: SEE APPROPRIATE INDUSTRY SPECIFICATION FOR LOCATION OF PIN 1

8. PACKAGED PER PACKAGING SPECIFICATION: PK-170432-900

9. CONFORMS TO PRODUCT SPECIFICATION: PS-170432-001

10. THIS PART CONFORMS TO CLASS C REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

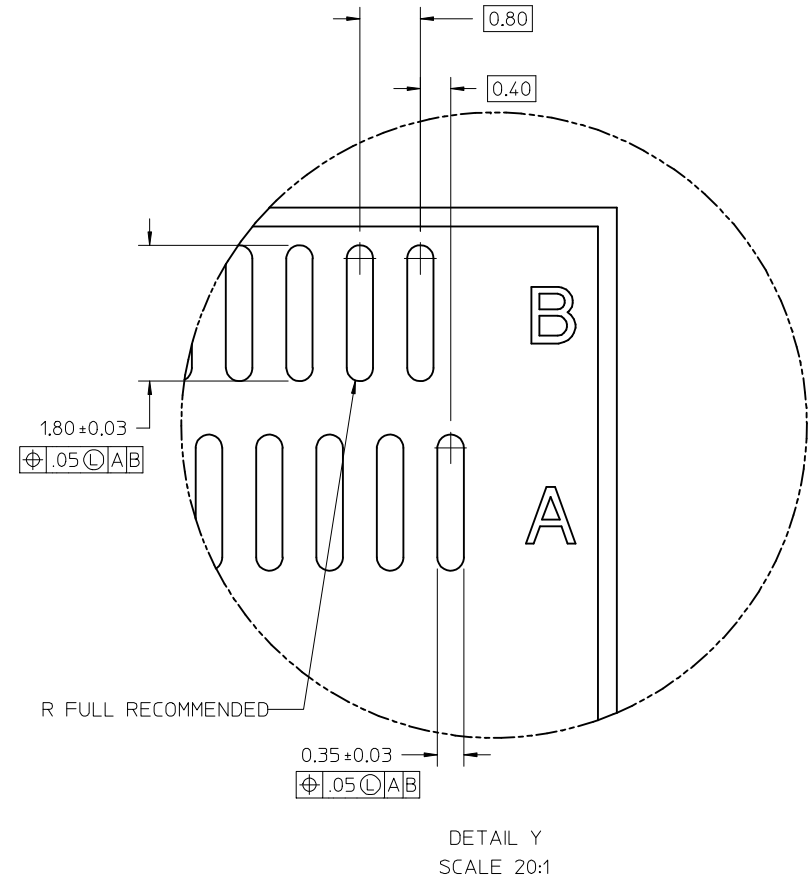
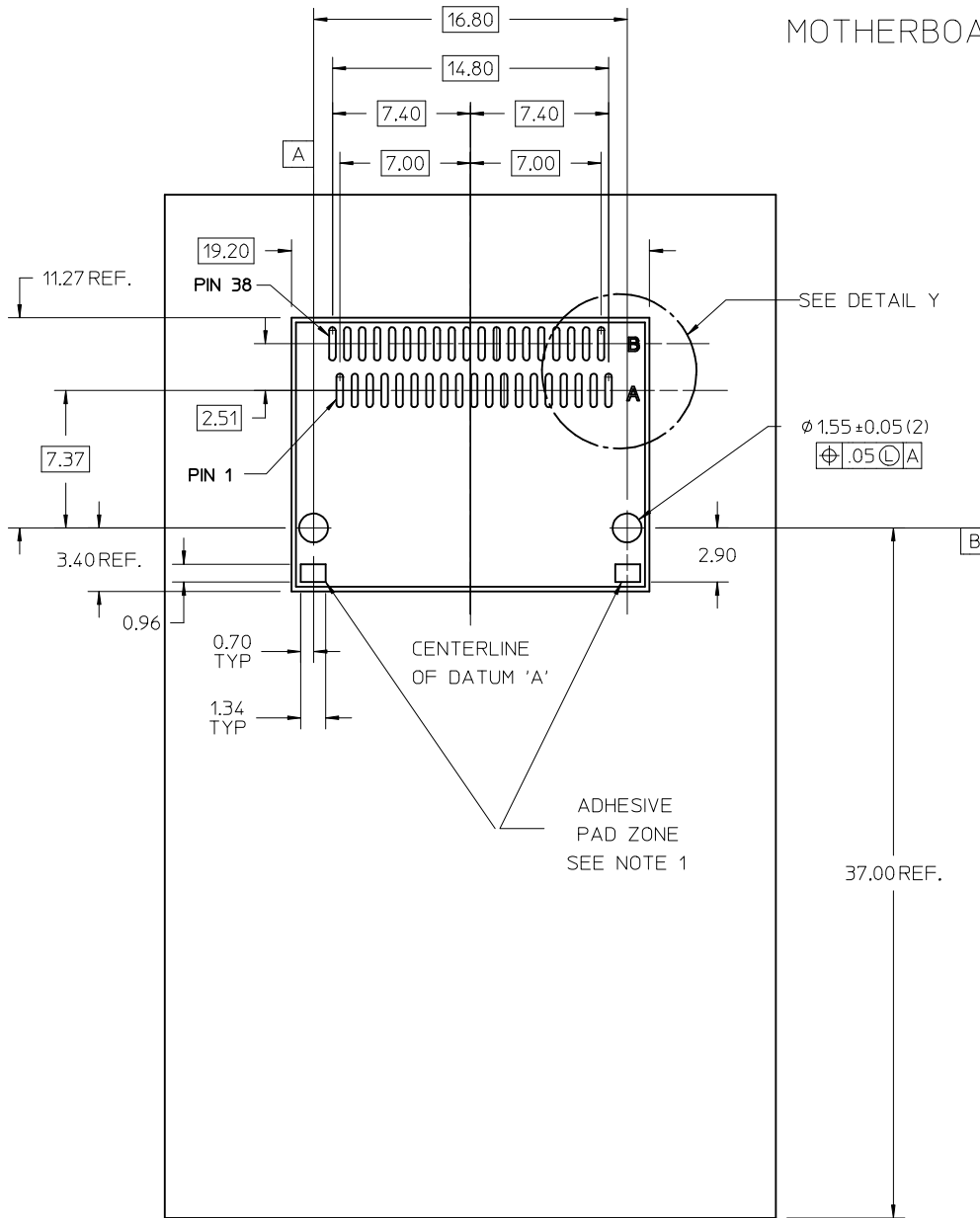
DATE CODE LOCATION
SEE NOTE 6



PART NUMBER	DESCRIPTION
170432-0001	PLATED PER NOTE 2
170432-0002	PLATED PER NOTE 3
170432-0003	PLATED PER NOTE 4

ADD OVERALL HEIGHT DIM. EC NO: S2018-0077 DRWNWZHA021 CHKD:CCTHE APPR:KACHLIC REV	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) mmINCH 4 PLACES±---±--- 3 PLACES±---±--- 2 PLACES±0.25±--- 1 PLACE±0.38±--- ANGULAR ±1/2°	DIMENSION STYLE MM ONLY DRAWN BY DATE JGONZALEZ012010/05/06 CHECKED BY DATE JJANTELEZ102010/05/06 APPROVED BY DATE MBANAKIS2011/11/04	SCALE 4:1 DESIGN UNITS METRIC THIRD ANGLE PROJECTION	TITLE ASSEMBLY ZQSFP+ 38 CIRCUIT	MOLEX MOLEX INCORPORATED DOCUMENT NO. SD-170432-002	SHEET NO. 1 OF 3
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

MOTHERBOARD FOOTPRINT RECOMMENDATION



- NOTES:
1. WHEN USING A TWO PASS REFLOW PROCESS WHERE THE CONNECTOR IS ON THE UNDERSIDE OF THE PCB DURING THE SECOND PASS, USE OF AN ADHESIVE IS RECOMMENDED.

SEE SHEET 1 EC NO: S2018-0077 DRAWN: JGONZALEZ01 CHKD: CJTEH APPR: JKACH.LC 2017/07/28 2017/08/15 2017/09/21	REV	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	TITLE ASSEMBLY ZQSFP+ 38 CIRCUIT	
					mm	INCH						
				4 PLACES	± ---	± ---	DRAWN BY	DATE	MOLEX MOLEX INCORPORATED			
				3 PLACES	± ---	± ---	CHECKED BY	DATE				
				2 PLACES	± 0.25	± ---	JJANTELEZ10	2010/05/06	DOCUMENT NO. SD-170432-002			
				1 PLACE	± 0.38	± ---	APPROVED BY	DATE				SHEET NO. 2 OF 3
				ANGULAR ±1/2°			MBANAKIS	2011/11/04	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			MATERIAL NO. SEE SHEET 1					
							SIZE					

